PTO/SB/08A (10-01)

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				Application Number	10/815 418			
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STA	TEMENT	BY A	APPLICANT	First Named Inventor	RONALD GENE FILIPPI			
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Sheet	1	of	2	Attorney Docket Number	YOR920040086US1 (163-32)			

			U.S. PAT	ENT DOCUMENTS	
Examiner		Decument Number Number- Kind Code ² (if know	Publication Date	Name of Patentee or Applicant of Cited Document	Pagos, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
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PTC/SB/08B (10-01)

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		OTHER PRIOR ART NON PATENT LITERATURE DOCUMENTS	
Examiner Initials	Cite No.1	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue aumher(s), publisher, city and/or country where published	Т
		HANCE H. HUSTON and C. PATRICK CLARKE; "Reliability Defect Detection and Screening during Processing - Theory and Implementation"; IEEE/IRPS; Jan.1992; pp. 268-275	
3/		R. G. FILIPPI et al.; "Thermal Cycle Reliability of Stacked Via Structures with Copper Metallization and an Organic Low-K Dielectric"; sent in Oct. 2003 to International Reliability Physics Symposium committee for later publishing; 4 pages (including 2004 IRPS Submission Cover Page and article)	
/		R. G. FILIPPI et al.; "Thermal Cycle Reliability of Stacked Via Structures with Copper Metallization and an Organic Low-K Dielectric"; IBM Hopewell Junction, NY Yorktown Heights, NY, Essex Junction, VT; February 20, 2004; 7 pages	
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